



STS9D8NH3LL

Dual N-channel 30V - 0.012Ω - 9A SO-8
Low on-resistance STripFET™ Power MOSFET

PRELIMINARY DATA

General features

Type		V _{DSS}	R _{DS(on)}	Qg	I _D
STS9D8NH3LL	Q ₁	30V	< 0.022Ω	7nC	8A
	Q ₂	30V	< 0.015	9nC	9A

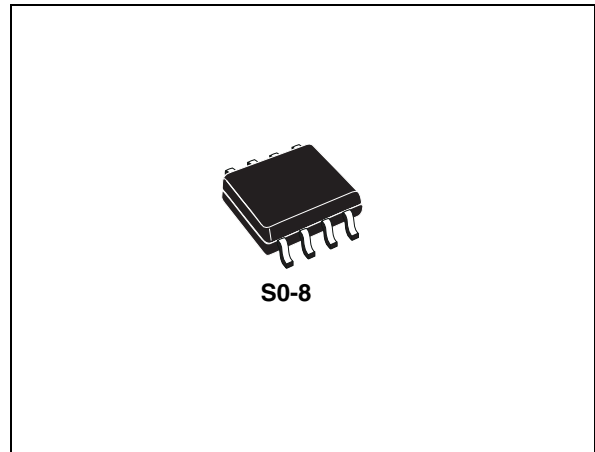
- Optimal R_{DS(on)} x Qg trade-off @ 4.5V
- Conduction losses reduced
- Switching losses reduced

Description

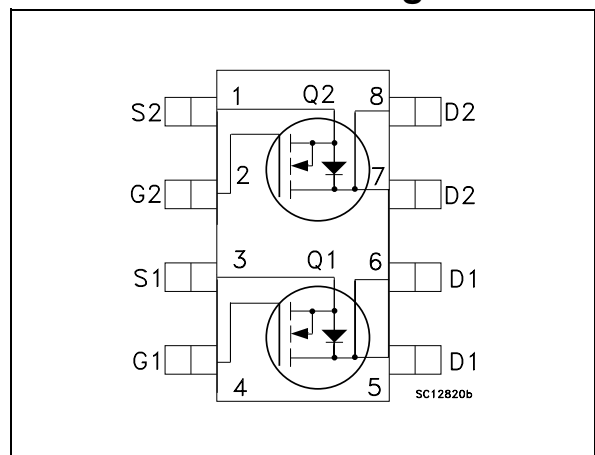
This device uses the latest advanced design rules of ST's STrip based technology. The Q1 and Q2 transistors, show respectively, the best gate charge and on-resistance for minimizing the switching and conduction losses. This application specific Power MOSFET has been designed to replace two SO-8 packages in DC-DC converters.

Applications

- Switching application



Internal schematic diagram



Order codes

Part number	Marking	Package	Packaging
STS9D8NH3LL	9D8H3LL-	SO-8	Tape & reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Type	Value	Unit
V_{DS}	Drain-source voltage ($v_{GS} = 0$)	Q_1	30	V
		Q_2	30	V
V_{GS}	Gate- source voltage	Q_1	± 16	V
		Q_2	± 16	V
I_D	Drain current (continuous) at $T_C = 25^\circ\text{C}$	Q_1	8	A
		Q_2	9	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$	Q_1	5	A
		Q_2	5.6	A
$I_{DM}^{(1)}$	Drain current (pulsed)	Q_1	32	A
		Q_2	36	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	Q_1	2	W
		Q_2	2	W

1. Pulse width limited by safe operating area

Table 2. Thermal data

R_{thj-a}	⁽¹⁾ Thermal resistance junction-ambient max	62.5	$^\circ\text{C/W}$
T_J	Thermal operating junction-ambient	150	$^\circ\text{C}$
T_{stg}	Storage temperature	-55 to 150	$^\circ\text{C}$

1. When mounted on 1 inch² FR-4 board, 2 oz. Cu., $t \leq 10\text{s}$

2 Electrical characteristics

($T_{CASE}=25^{\circ}\text{C}$ unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test conditions	Type	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown voltage	$I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0$	Q_1 Q_2	30 30			V V
I_{DSS}	Zero gate voltage Drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}$	Q_1 Q_2			1 1	μA μA
I_{DSS}	Zero gate voltage Drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}$ @ 125°C	Q_1 Q_2			10 10	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 16\text{V}$	Q_1 Q_2			± 100 ± 100	nA nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	Q_1 Q_2	1 1			V V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{V}$, $I_D = 4\text{A}$ $V_{GS} = 10\text{V}$, $I_D = 4.5\text{A}$	Q_1 Q_2		0.018 0.012	0.022 0.015	Ω Ω
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 4.5\text{V}$, $I_D = 4\text{A}$ $V_{GS} = 4.5\text{V}$, $I_D = 4.5\text{A}$	Q_1 Q_2		0.020 0.014	0.025 0.0175	Ω Ω

Table 4. Dynamic

Symbol	Parameter	Test conditions	Type	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 25\text{V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$	Q_1 Q_2		857 965		pF pF
C_{oss}	Output capacitance		Q_1 Q_2		147 285		pF pF
C_{rss}	Reverse transfer capacitance		Q_1 Q_2		20 38		pF pF
Q_g	Total gate charge	$V_{DD} = 15\text{V}$, $I_D = 8\text{A}$, $V_{GS} = 5\text{V}$ (see Figure 2)	Q_1 Q_2		7 9	10 12	nC nC
Q_{gs}	Gate-source charge		Q_1 Q_2		2.5 3.7		nC nC
Q_{gd}	Gate-drain charge		Q_1 Q_2		2.3 3		nC nC

Table 5. Switching times

Symbol	Parameter	Test conditions	Type	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD}=15\text{ V}$, $I_D=4A$, $R_G=4.7\Omega$, $V_{GS}= 4.5V$ <i>(see Figure 4)</i>	Q_1		12		ns
t_r	Rise time		Q_2		15		ns
			Q_1		14.5		ns
			Q_2		32		ns
$t_{d(off)}$	Turn-off delay time	$V_{DD}=15\text{ V}$, $I_D=4A$, $R_G=4.7\Omega$, $V_{GS}= 4.5V$ <i>(see Figure 4)</i>	Q_1		23		ns
t_f	Fall time		Q_2		18		ns
			Q_1		8		ns
			Q_2		8.5		ns

Table 6. Source drain diode

Symbol	Parameter	Test conditions	Type	Min	Typ.	Max	Unit
I_{SD}	Source-drain current	$V_{DD}=15V, I_D=4A$ $R_G=4.7\Omega, V_{GS}=4.5V$	Q_1			8	A
			Q_2			9	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)	$V_{DD}=15V, I_D=4A$ $R_G=4.7\Omega, V_{GS}=4.5V$	Q_1			32	A
			Q_2			36	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 8A, V_{GS} = 0$	Q_1			1.5	V
			Q_2			1.3	V
t_{rr}	Reverse recovery time	$I_{SD} = 8A, V_{DD} = 15V$ $di/dt = 100A/\mu s,$ $T_j = 150^{\circ}C$ <i>(see Figure 3)</i>	Q_1		15		ns
Q_{rr}	Reverse recovery charge		Q_2		24		ns
			Q_1		5.7		nC
I_{RRM}	Reverse recovery current		Q_2		17.4		nC
			Q_1		0.76		A
		Q_2		1.54		A	

1. Pulse width limited by safe operating area.

2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

3 Test circuit

Figure 1. Switching times test circuit for resistive load

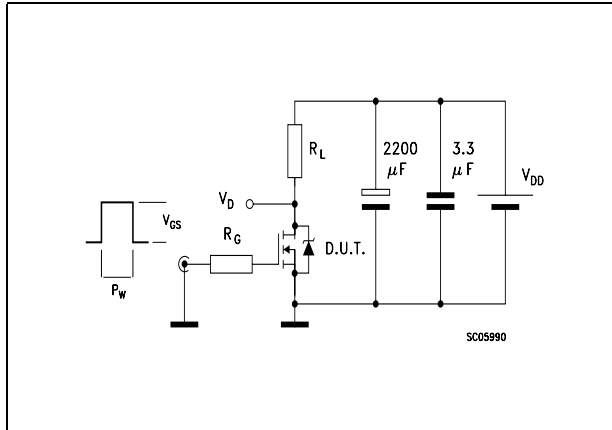


Figure 2. Gate charge test circuit

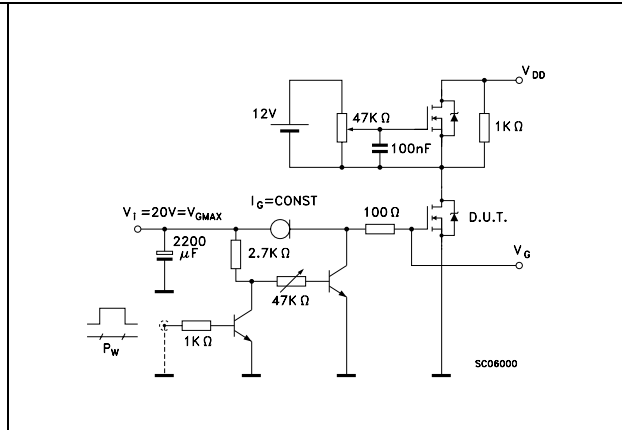


Figure 3. Test circuit for inductive load switching and diode recovery times

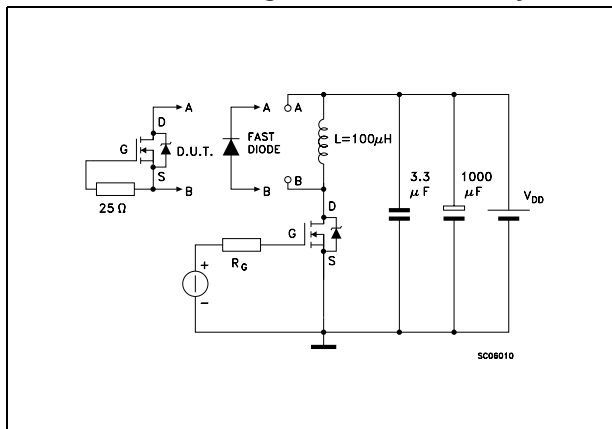


Figure 4. Unclamped Inductive load test circuit

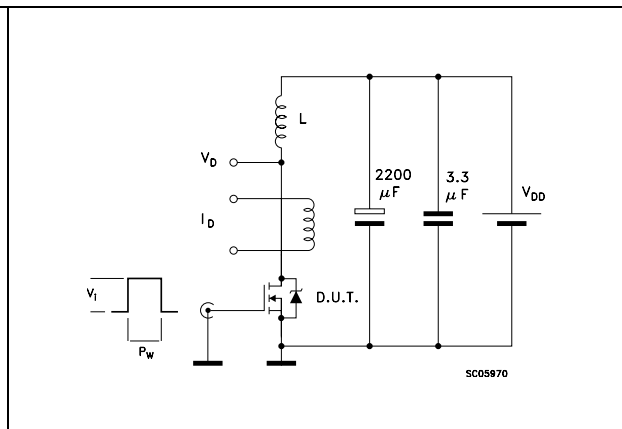


Figure 5. Unclamped inductive waveform

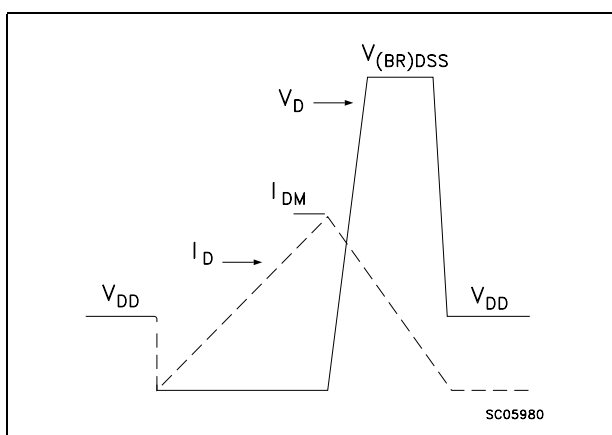
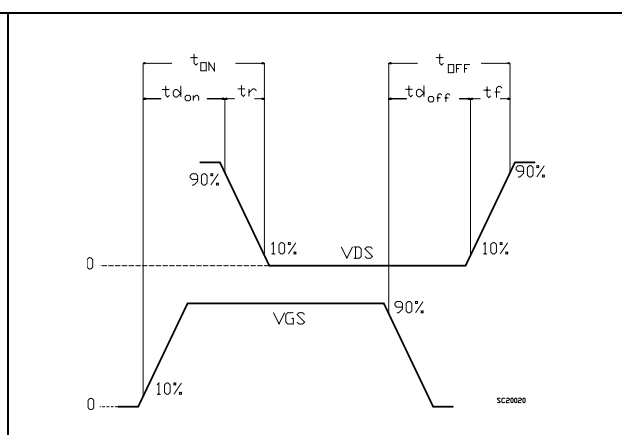


Figure 6. Switching time waveform

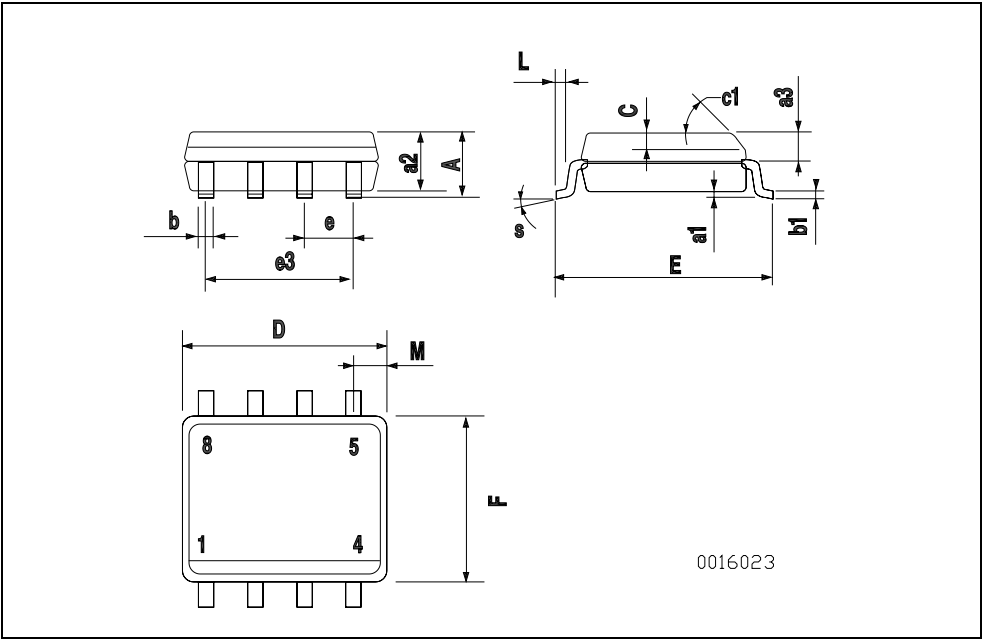


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at : www.st.com

SO-8 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
C	0.25		0.5	0.010		0.019
c1	45 (typ.)					
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
M			0.6			0.023
S	8 (max.)					



5 Revision history

Table 7. Revision history

Date	Revision	Changes
05-Jan-2007	1	First release
06-Mar-2007	2	Some value changed on Table 3 ($R_{DS(on)}$ for Q2)

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